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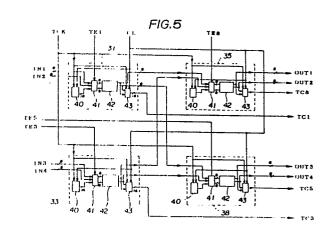
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- Representative: Joly, Jean-Jacques et al CABINET BEAU DE LOMENIE 55, rue d'Amsterdam F-75008 Paris(FR)
- Semiconductor integrated circuit with a test function.
- (57) A semiconductor integrated circuit comprises a plurality of integrated circuit blocks (31 - 39) constituted on a wafer (30), the integrated circuit blocks being arbitrarily electrically connected to each other so as to form a system. Each of the integrated circuit blocks comprises a logical operating circuit (42) for carrying out a logical operation; a pseudorandom pattern generating circuit (40) for generating a pseudo-random pattern signal; switching circuit (41) for selecting either an input signal to be processed by the logical operating circuit or the pseudo-random pattern signal in response to a test enabling signal (TE1 - TE9) which is independently applied to each integrated circuit block so that each integrated circuit block is independently set to either a test mode or a normal mode and for outputting the $oldsymbol{\triangleleft}$ selected signal to the logical operating circuit; and a data compressing circuit (43) for compressing an output data signal of the logical operating circuit.





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EUROPEAN SEARCH REPORT

EP 87 40 2872

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Category	Citation of document with in of relevant pa	ndication, where appropriate, ssages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int. Cl. 4)
Y	ELECTRONIC DESIGN, 11th July 1985, pag NL; M. BEEDIE: "Tes tolerance emerge as wafer-scale confere * Page 63, column 1 column 2; page 64, 39-46 *	es 63-64, Schiphol, ting, fault top issues at nce" , last paragraph - column 2, lines	1,3,4	G 01 R 31/28
A	* Page 63, column 3	, lines 28-40 *	6	
Y	York, US; D.K. BHAV supercells" * Page 138, paragra division (POLYDIV)	ton, 2nd-5th s 135-139, IEEE, New SAR; "Self-testing ph "Polynomial Scheme" *	1,3,4	
Α	* Page 138, point "	FSR" *	7	
P,X	PROCEEDINGS OF THE INTEGRATED CIRCUITS Portland, 4th-7th M 207-210, IEEE, New YAMASHITA et al.: "170,000-gate FFT pr built-in test circu* Whole article *	CONFERENCE, ay 1987, pages York, US; K. A wafer-scale ocessor with its"	1-7	G 06 F 11/26 G 01 R 31/28 G 06 F 11/20
	Place of search	Date of completion of the search	h	Examiner
I HE	HAGUE	12-12-1989	SARA	ASUA GARCIA L.
X: part Y: part doc A: tech O: non	CATEGORY OF CITED DOCUMENT ticularly relevant if taken alone ticularly relevant if combined with and ument of the same category anological background written disclosure rmediate document	E : earlier pater after the fill ther D : document c L : document ci	inciple underlying the nt document, but publing date ited in the application ited for other reasons the same patent famil	ished on, or